

Amendments to the Claims

Please amend the claims as follows:

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1. (Currently Amended) A semiconductor device comprising a bond pad structure, which bond pad structure comprises a bond pad disposed above a at least one layered structure that increases structural integrity of the bond pad structure, wherein the layered structure comprises a top and bottom metal layer and a at least one layer of dielectric material, and a plurality of equally spaced parallel via lines that connect the top and bottom metal layers and partition the at least one dielectric area characterized in that via lines are present in the layer of a dielectric material, which via lines are connected to the metal layer to form isolated areas filled with dielectric material.
 2. (Original) A semiconductor device as claimed in claim 1, wherein the via lines are lines of tungsten.
 3. (Previously Amended) A semiconductor device as claimed in claim 1, wherein a stack of layered structures is present.
 4. (Original) A semiconductor device as claimed in claim 3, wherein the metal layer in each layered structure is a metal plate.

5. (Original) A semiconductor device as claimed in claim 4, wherein the top and bottom metal layers of the stack are metal plates, and the intermediate metal layer or layers are parallel metal lines.

6. (Original) A semiconductor device as claimed in claim 5, wherein the metal lines are patterned in the form of a grid.

7. (Previously Amended) A semiconductor device as claimed in claim 1, wherein the via lines are patterned in the form of a grid.

8-11 (Cancelled)